

## Tra-Con Tra-Duct 2956 Low Ion Snap Cure Silver Epoxy Adhesive

Category : Polymer , Adhesive , Thermoset , Epoxy , Filled/Reinforced Thermoset

### Material Notes:

TRA-DUCT 2956 is recommended for the bonding and sealing of electronic components where a combination of electrical and mechanical properties are required. This two-part, smooth, paste system of silver filled epoxy is free of solvents and copper or carbon additives. It develops strong durable electrically and thermally conducting bonds and coatings between a number of materials such as metals, ceramics, glass and plastic laminates. TRA- DUCT 2956 cures at room temperature, which makes it extremely useful for bonding heat sensitive components where hot-soldering is impractical. Other common uses include the assembly and repair of electrical modules, printed circuits, wave guides, flat cable and high frequency shields. It is an excellent product for dot dispensing through needles as small as 6 mils.

Information provided by Tra-Con Inc.

Order this product through the following link:

[http://www.lookpolymers.com/polymer\\_Tra-Con-Tra-Duct-2956-Low-Ion-Snap-Cure-Silver-Epoxy-Adhesive.php](http://www.lookpolymers.com/polymer_Tra-Con-Tra-Duct-2956-Low-Ion-Snap-Cure-Silver-Epoxy-Adhesive.php)

Physical Properties	Metric	English	Comments
Specific Gravity	2.40 g/cc	2.40 g/cc	Mixed
Viscosity	145000 cP @Temperature 25.0 °C	145000 cP @Temperature 77.0 °F	After mixing

Mechanical Properties	Metric	English	Comments
Hardness, Shore D	80	80	
Adhesive Bond Strength	6.89 MPa	1000 psi	Lap shear, alum to alum, 2 min @ 150°C
	6.89 MPa	1000 psi	Lap shear, alum to alum, 5 min @ 100°C
	6.89 MPa	1000 psi	Lap shear, alum to alum, 72 hrs @ 25°C

Thermal Properties	Metric	English	Comments
CTE, linear	49.0 $\mu\text{m}/\text{m}\cdot^\circ\text{C}$ @Temperature 20.0 °C	27.2 $\mu\text{in}/\text{in}\cdot^\circ\text{F}$ @Temperature 68.0 °F	
Thermal Conductivity	1.50 W/m-K	10.4 BTU-in/hr-ft <sup>2</sup> -°F	
Maximum Service Temperature, Air	175 °C	347 °F	
Minimum Service Temperature, Air	-55.0 °C	-67.0 °F	
Glass Transition Temp, Tg	47.0 °C	117 °F	Ultimate Tg

Electrical Properties	Metric	English	Comments
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Electrical Properties	Metric <sup>1</sup> 0 ohm-cm	English <sup>1</sup> 0 ohm-cm	Comments <sup>2</sup> @ 25°C
	0.00020 ohm-cm	0.00020 ohm-cm	cured 5 min @ 100°C
	0.00050 ohm-cm	0.00050 ohm-cm	cured 2 min @ 150°C

Processing Properties	Metric	English	Comments
Cure Time	2.00 min	0.0333 hour	
	@Temperature 150 °C	@Temperature 302 °F	
	5760 min	96.0 hour	
	@Temperature 25.0 °C	@Temperature 77.0 °F	
Pot Life	720 min	720 min	

Descriptive Properties	Value	Comments
Color	Silver	
Mix Ratio, parts by weight	100/6	Resin/Hardener
Thixotropic Index	3.9	5 rpm/50 rpm

## Contact Songhan Plastic Technology Co.,Ltd.

Website : [www.lookpolymers.com](http://www.lookpolymers.com)

Email : [sales@lookpolymers.com](mailto:sales@lookpolymers.com)

Tel : +86 021-51131842

Mobile : +86 13061808058

Skype : lookpolymers

Address : United North Road 215,Fengxian District, Shanghai City,China